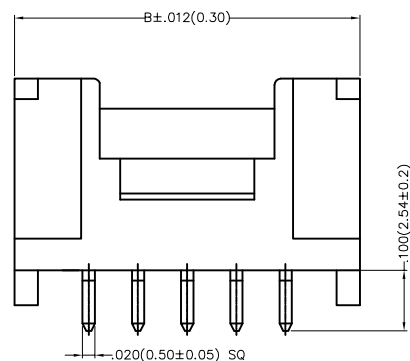
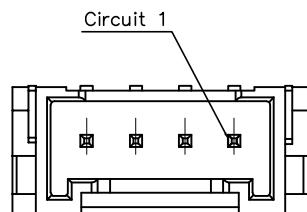
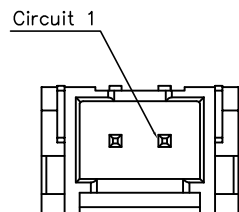
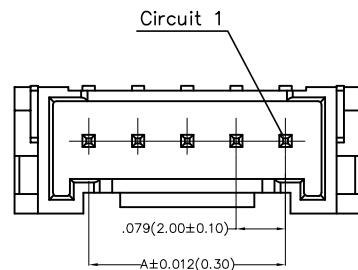
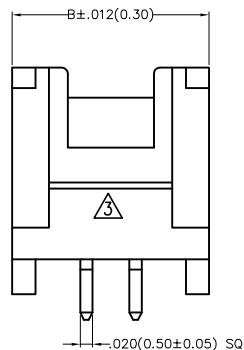


A
B
C
D
E
F

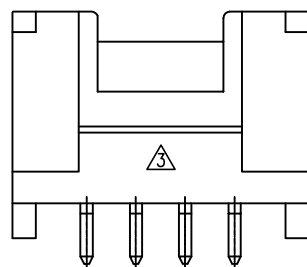
12345



5-16Circuits



2Circuits



3-4Circuits

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	①	MPQ: Change 800 pcs into 1,000 pcs / reel	28/FEB/20	KATE	CERRY
2	②	LCP added for plastic materials	14/FEB/22	MATT	CERRY
3	③	1:Upadte the structure 2:Plastic materials PA9T replaces LCP	02/JUN/23	MATT	LEO
4	④	Update packaging	02/JUN/23	MATT	LEO

Electrical

Current Rating: 2.0A AC(rms)/DC

Voltage Rating: 125V AC(rms)/DC

Contact Resistance: 20 mΩ Max

Insulation Resistance: 1000 MΩ MIN

Withstanding Voltage: 800V AC r.m.s

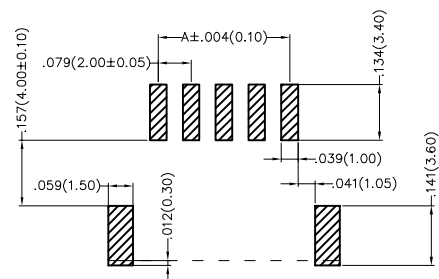
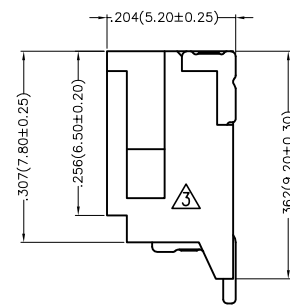
Temperature Range—Operating: -25°C~+85°C

Material and Plating

Housing: PA6T/PA9T(UL 94V-0)②③

Contact Pin: Brass

Plating: Tin Plated



Recommended P.C.Board Layout

Ordering Information

FWF 200 19 — S XX B 2 X W5 M
1 2 3 4 5 6 7 8 9 10

1	Category FWF—Wafer	2	Series Number 200—Pitch2.0mm	3	Distinction No. 19	4	Row Option S—Single Row	5	Circuits XX	6	Entry Angle B—90° Angle
7	Plating 2—Tin Plated	8	Material—Resin 4—PA6T 5—PA9T ②③	9	Color—Resin W5—Natural	10	Packaging M—Reel				

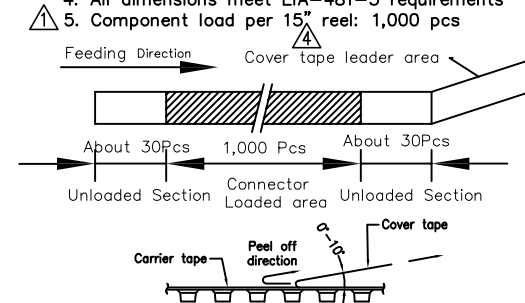
 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 18/JUN/13	PART NO. FWF20019--SXXB2XW5M	ITEM NO. FWF20019	 Building Technology Cornerstone	
DESIGN UNITS Inch (metric)		X.±.012(0.30)	X.±5°	CHECKED BY	DATE	TITLE Wire to Board (Wafer) Pitch 2.0mm 90° Angl (SMT)		REV 4 SHEET NO. 1/3	
		X.X±.008(0.20)	X.±2°	CHERRY	18/JUN/13				
		SCALE 5:1	SIZE A4	X.XX±.006(0.15)	.XX'±1°	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		X.XXX±.004(0.10)	.XXX±0.5°	KEVIN	18/JUN/13				

12345678

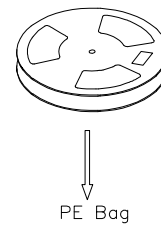
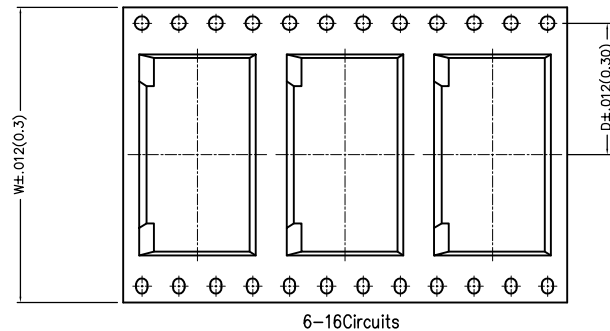
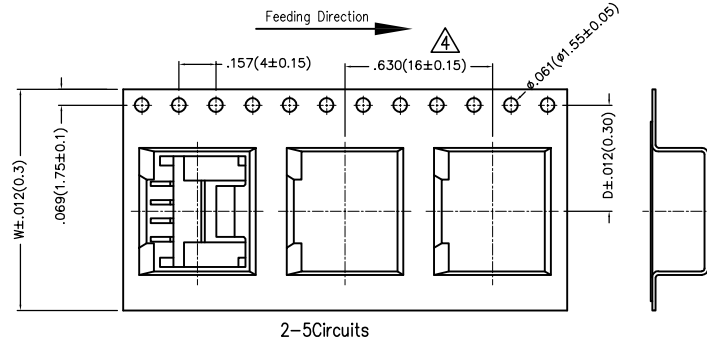
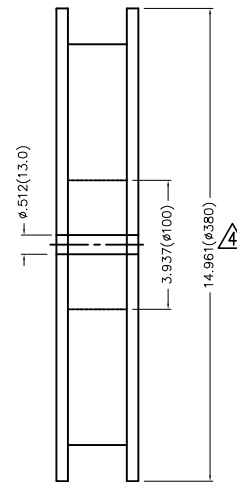
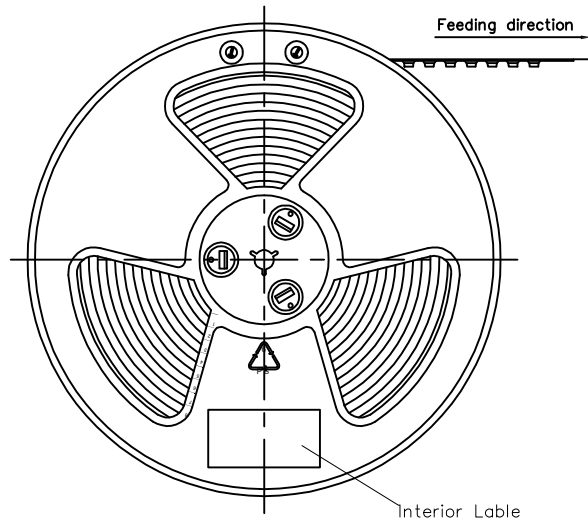
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Note:

1. 10 sprocket hole cumulative tolerance ± 0.2
2. Carrier camber is within 1.0mm in 100mm
3. Material: White Conductive polystyrene Alloy 100% recyclable
4. All dimensions meet EIA-481-3 requirements
5. Component load per 15" reel: 1,000 pcs

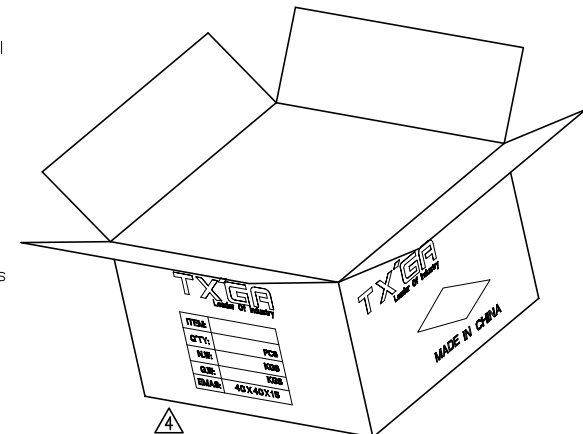


Circuits (n)	Dimensions(in/mm)		Circuits (n)	Dimensions(in/mm)	
	D	W		D	W
2	.295(7.50)	.630(16.00)	10	.795(20.20)	1.732(44.00)
3	.295(7.50)	.630(16.00)	11	.795(20.20)	1.732(44.00)
4	.453(11.50)	.945(24.00)	12	.795(20.20)	1.732(44.00)
5	.453(11.50)	.945(24.00)	13	.795(20.20)	1.732(44.00)
6	.453(11.50)	.945(24.00)	14	.795(20.20)	1.732(44.00)
7	.559(14.20)	1.260(32.00)	15	.795(20.20)	1.732(44.00)
8	.559(14.20)	1.260(32.00)	16	.795(20.20)	1.732(44.00)
9	.559(14.20)	1.260(32.00)			



1,000 pcs/Reel

Drying agent/pcs



 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY	DATE	PART NO.	ITEM NO.	 Building Technology Cornerstone	
				FRANK	18/JUN/13	FWF20019-SXXB2XW5M	FWF20019		
DESIGN UNITS Inch (metric)		X.±.012(0.30)	X.±5°	CHECKED BY	DATE	TITLE Wire to Board (Wafer) Pitch 2.0mm 90° Angle (SMT)		REV 4 SHEET NO. 3/3	
		X.X±.008(0.20)	.X'±2°	CHERRY	18/JUN/13				
		SCALE 5:1	SIZE A4	X.XX±.006(0.15)	.XX'±1°	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		X.XXX±.004(0.10)	.XXX'±0.5°	KEVIN	18/JUN/13				